# **Silicon Controlled Rectifiers**

## **Reverse Blocking Thyristors**

Designed primarily for half-wave ac control applications, such as motor controls, heating controls and power supplies; or wherever half-wave silicon gate-controlled, solid-state devices are needed.

#### Features

- Glass Passivated Junctions with Center Gate Geometry for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Blocking Voltage to 800 V
- These are Pb–Free Devices

#### **MAXIMUM RATINGS\*** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
$\begin{array}{l} \mbox{Peak Repetitive Off-State Voltage (Note 1)} \\ (T_J = -40 \ to \ 125^\circ C, \ Sine \ Wave \ 50 \ to \ 60 \\ \ Hz; \ Gate \ Open) \\ & 2N6400 \\ & 2N6401 \\ & 2N6402 \\ & 2N6403 \\ & 2N6404 \\ & 2N6405 \end{array}$	V <sub>DRM,</sub> V <sub>RRM</sub>	50 100 200 400 600 800	V
On-State Current RMS (180° Conduction Angles; $T_C$ = 100°C)	I <sub>T(RMS)</sub>	16	A
Average On-State Current (180° Conduction Angles; $T_C$ = 100°C)	I <sub>T(AV)</sub>	10	A
Peak Non-repetitive Surge Current (1/2 Cycle, Sine Wave 60 Hz, $T_J = 25^{\circ}$ C)	I <sub>TSM</sub>	160	A
Circuit Fusing Considerations (t = 8.3 ms)	l <sup>2</sup> t	145	A <sup>2</sup> s
Forward Peak Gate Power (Pulse Width $\leq$ 1.0 $\mu s,T_C$ = 100°C)	P <sub>GM</sub>	20	W
Forward Average Gate Power (t = 8.3 ms, $T_C = 100^{\circ}C$ )	P <sub>G(AV)</sub>	0.5	W
Forward Peak Gate Current (Pulse Width $\leq$ 1.0 $\mu s,T_C$ = 100°C)	I <sub>GM</sub>	2.0	A
Operating Junction Temperature Range	TJ	-40 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

 V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.



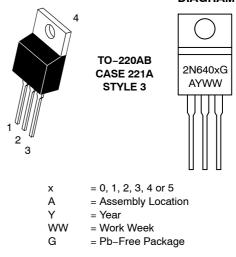
## **ON Semiconductor®**

http://onsemi.com

## SCRs 16 AMPERES RMS 50 thru 800 VOLTS







	PIN ASSIGNMENT
1	Cathode
2	Anode
3	Gate
4	Anode

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

Semiconductor Components Industries, LLC, 2012 November, 2012 – Rev. 6

#### THERMAL CHARACTERISTICS

Characteristic		Symbol	Ма	ax	U	nit
Thermal Resistance, Junction-to-Case		$R_{\thetaJC}$	1.	5	°C	W/
Maximum Lead Temperature for Soldering Purposes 1/8 in from Case for 10 Seconds		TL	260		°C	
ELECTRICAL CHARACTERISTICS ( $T_C = 25^{\circ}C$	C unless otherwise noted.)					
Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					-	
*Peak Repetitive Forward or Reverse Blocking Cu $(V_{AK} = Rated V_{DRM} \text{ or } V_{RRM}, Gate Open)$	rrent T <sub>J</sub> = 25°C T <sub>J</sub> = 125°C	I <sub>DRM</sub> , I <sub>RRM</sub>	_		10 2.0	μA mA
ON CHARACTERISTICS						
*Peak Forward On–State Voltage ( $I_{TM}$ = 32 A Peak, I	Pulse Width $\leq$ 1 ms, Duty Cycle $\leq$ 2%)	V <sub>TM</sub>	-	-	1.7	V
*Gate Trigger Current (Continuous dc) (V <sub>D</sub> = 12 Vdc, R <sub>L</sub> = 100 $\Omega$ )	$T_{C} = 25^{\circ}C$ $T_{C} = -40^{\circ}C$	I <sub>GT</sub>		9.0 -	30 60	mA
*Gate Trigger Voltage (Continuous dc) ( $V_D$ = 12 Vdc, $R_L$ = 100 $\Omega$ )	$T_{C} = 25^{\circ}C$ $T_{C} = -40^{\circ}C$	V <sub>GT</sub>		0.7	1.5 2.5	V
Gate Non-Trigger Voltage ( $V_D$ = 12 Vdc, $R_L$ = 100 $\Omega$	?), T <sub>C</sub> = +125°C	V <sub>GD</sub>	0.2	-	-	V
*Holding Current (V <sub>D</sub> = 12 Vdc, Initiating Current = 200 mA, Gate	T <sub>C</sub> = 25°C Open) *T <sub>C</sub> = -40°C	IH	-	18 _	40 60	mA
Turn-On Time ( $I_{TM}$ = 16 A, $I_{GT}$ = 40 mAdc, $V_D$ = R	ated V <sub>DRM</sub> )	t <sub>gt</sub>	-	1.0	-	μs
Turn-Off Time ( $I_{TM}$ = 16 A, $I_R$ = 16 A, $V_D$ = Rated V	$V_{DRM}$ ) T <sub>C</sub> = 25°C T <sub>J</sub> = +125°C	tq		15 35		μs
DYNAMIC CHARACTERISTICS						
Critical Rate-of-Rise of Off-State Voltage ( $V_D = Rateria T_J = +125^{\circ}C$	ated V <sub>DRM</sub> , Exponential Waveform)	dv/dt	-	50	-	V/µs

\*Indicates JEDEC Registered Data.

## Voltage Current Characteristic of SCR

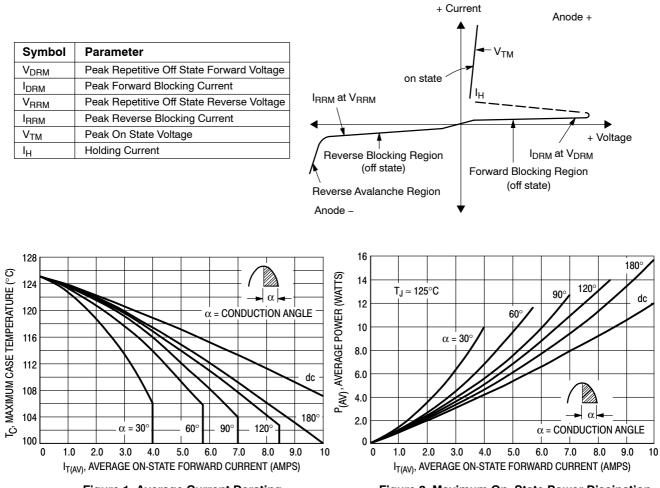
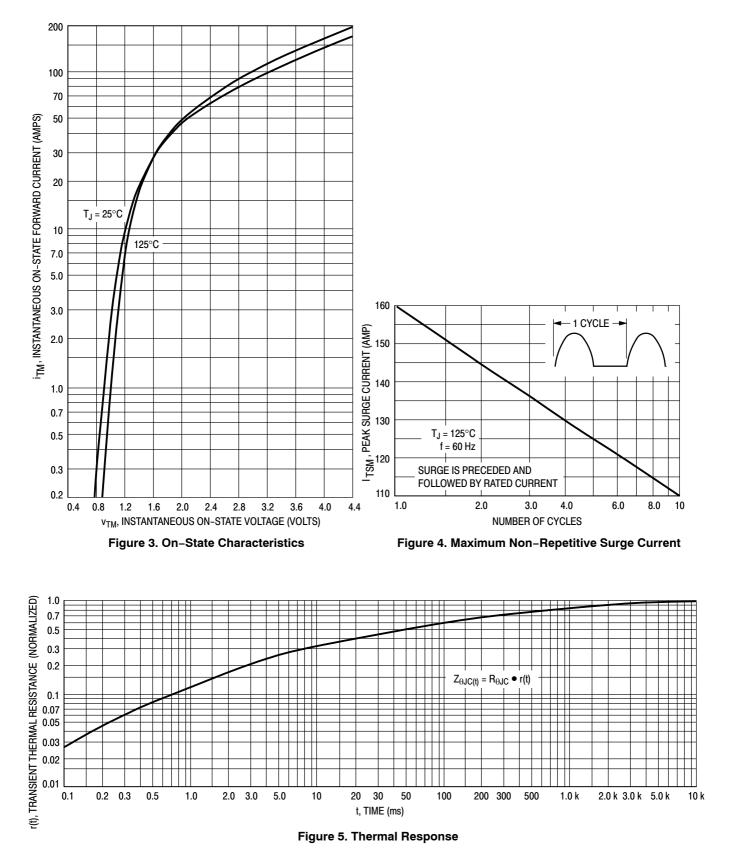
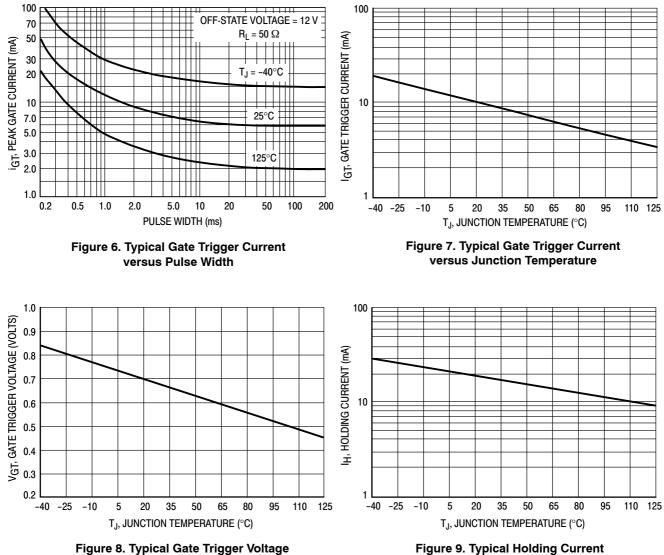


Figure 1. Average Current Derating

Figure 2. Maximum On-State Power Dissipation



#### **TYPICAL CHARACTERISTICS**



versus Junction Temperature

Figure 9. Typical Holding Current versus Junction Temperature

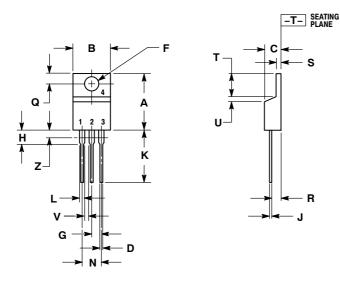
#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
2N6400G	TO-220AB (Pb-Free)	
2N6401G	TO-220AB (Pb-Free)	500 Haita / Davi
2N6402G	TO-220AB (Pb-Free)	500 Units / Box
2N6403G	TO-220AB (Pb-Free)	
2N6403TG	TO-220AB (Pb-Free)	50 Units / Rail
2N6404G	TO-220AB (Pb-Free)	500 Units / Box
2N6405G	TO-220AB (Pb-Free)	SUD UTIRS / BOX

#### PACKAGE DIMENSIONS

TO-220 CASE 221A-07 ISSUE O

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	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.014	0.022	0.36	0.55
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
Ν	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
z		0.080		2.04

1. DIMENSIONING AND TOLERANCING PER ANSI

2. CONTROLLING DIMENSION: INCH.

NOTES

Y14.5M, 1982.

2 ANODE 3. GATE 4. ANODE

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